AUTOMOTIVE GRADE

RoHS

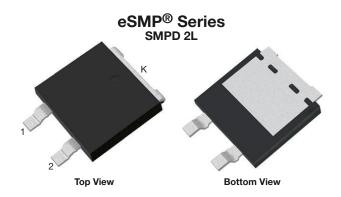
HALOGEN

FREE



Vishay General Semiconductor

Surface-Mount High Voltage Rectifier



LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS			
I _{F(AV)}	30 A		
V _{RRM}	1200 V		
I _{FSM}	300		
V_F at $I_F = 30 \text{ A} (T_J = 150 ^{\circ}\text{C})$	1.01		
I _R	10 μΑ		
T _J max.	175 °C		
Package	SMPD 2L		
Circuit configuration	Single		

FEATURES

 Creepage and clearance distance 3.7 mm typical



• Ideal for automated placement

• Oxide planar chip junction

Low forward voltage drop

AEC-Q101 qualified

 Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

 Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

TYPICAL APPLICATIONS

- ON Board charger (OBC)
- · Charging stations
- Bridge function

MECHANICAL DATA

Case: SMPD 2L

Molding compound meets UL 94 V-0 flammability rating Base P/N-M3 - halogen-free, RoHS-compliant, and

commercial grade

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

7.EO Q TO T qualifica

Terminals: matte tin plated leads, solderable per

J-STD-002 and JESD 22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

Polarity: as marked

MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted)				
PARAMETER	SYMBOL	SE30DT12	UNIT	
Device marking code		SE30DT12	V	
Maximum repetitive peak reverse voltage	V_{RRM}	1200	V	
Maximum DC forward current	I _F ⁽¹⁾	30	Α	
	I _F ⁽²⁾	3.5		
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	I _{FSM}	300	А	
Operating junction and storage temperature range	T _J , T _{STG}	-55 to +175	°C	

Notes

(1) With heatsink

(2) Free air, mounted on recommended copper pad area



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ELECTRICAL CHARACTERISTICS (T _J = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I _F = 15 A	T _{.1} = 25 °C	V _F ⁽¹⁾	1.03	-	V
	I _F = 30 A	1j=25 C		1.16	1.29	
	I _F = 15 A	T _J = 150 °C		0.87	-	
	I _F = 30 A			1.01	-	
Reverse current	Rated V _R	T _J = 25 °C	I _R ⁽²⁾	-	10	μА
	nated v _R	T _J = 150 °C		62	300	
Typical reverse recovery time	I _F = 0.5 A, I _R = 1.0 A, I _{rr} = 0.25 A		t _{rr}	3.4	-	μs
Typical junction capacitance	4.0 V, 1 MHz		CJ	132	-	pF

Notes

 $\stackrel{(1)}{\ldots}$ Pulse test: 300 μs pulse width, 1 % duty cycle

(2) Pulse test: Pulse width \leq 40 ms

THERMAL CHARACTERISTICS (T _A = 25 °c unless otherwise noted)				
PARAMETER	SYMBOL SE30DT12 UN			
Typical thormal registance	R _{θJA} (1)(2)	52	°C/W	
Typical thermal resistance	R _{0JM} (3)	1.5		

Notes

 $^{(1)}$ The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$

(2) Thermal resistance junction-to-ambient to follow JEDEC® 51-2A, device mounted on FR4 PCB, 2 oz. standard footprint (3) Thermal resistance junction-to-mount to follow JEDEC® 51-14 transient dual interface test method (TDIM)

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
SE30DT12-M3/I	0.52	I	2000 / reel	13" diameter plastic tape and reel
SE30DT12HM3/I (1)	0.52	I	2000 / reel	13" diameter plastic tape and reel

Note

(1) AEC-Q101 qualified

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RATINGS AND CHARACTERISTICS CURVES ($T_A = 25$ °C unless otherwise noted)

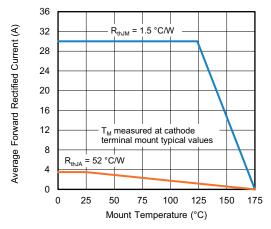


Fig. 1 - Forward Current Derating Curve

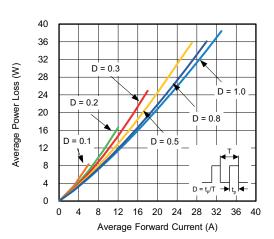


Fig. 2 - Forward Power Loss Characteristics

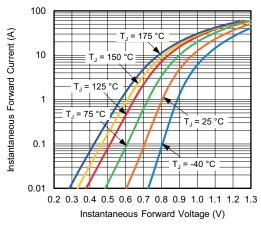


Fig. 3 - Typical Instantaneous Forward Characteristics

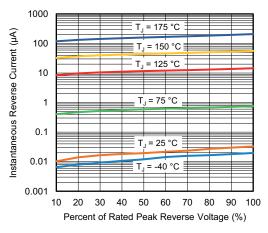


Fig. 4 - Typical Reverse Leakage Characteristics

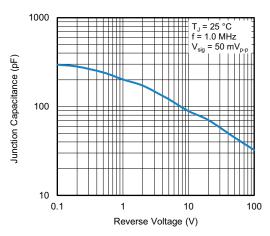


Fig. 5 - Typical Junction Capacitance

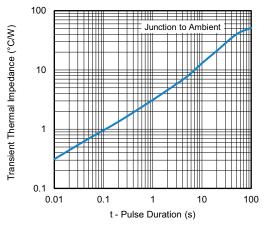


Fig. 6 - Typical Transient Thermal Impedance



0.354 (8.99) 0.338 (8.59)

0.063 (1.60)

0.047 (1.20)

 $\frac{0.200}{(5.08)}$ NOM.

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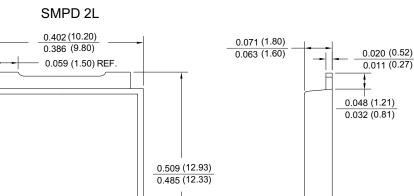
0 to 0.01 (0 to 0.254) 0.069 (1.74) 0.053 (1.34)

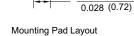
0.020 (0.52)

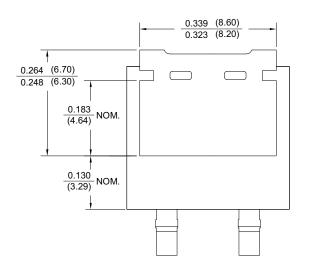
0.011 (0.27)

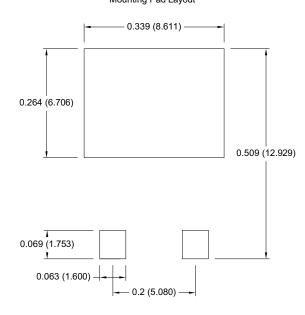
0.052 (1.32)

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)









Note

• The suggested mounting pad layout is provided for reference only, as actual pad layouts may vary depending on application



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